I. General description

- The ULTRA FLEX tests and characterizes LSI and VLSI devices microprocessors and their support chips, SOC (system on chip), High speed disk drive, Network switching, Chipset, Graphics, Hyper Transport, Rapid I/O, PCI Express, SATA.

II. System features

- Device engineering and characterization
- Production testing of devices in wafer and packaged forms
- QA and reliability testing, incoming inspection
- CAE link with VAX/VMS and UNIX software
- Internal reference for timing and analogic traceable to the National Institute of Standards and Technology (NIST)
III. Configuration

- One test head with 640 pins I/O
- Speed license for:
  - 320 pins at 200 Mbps (HSDM)
  - 128 pins at 400 Mbps (HSDM)
  - 128 pins at 800 Mbps (HSDM)
  - 64 pins at 3200 Mbps (SG6B)

  2 kind of electronics pins
  Single Ended pin Electronics: HSDM (edge accuracy +/- 150 ps)
  Differential Pin Electronics: SB6G

- Pattern depth 32 M vectors
- 32 dynamic edge set for all pins
- Driver specification VH/VL +6v to –1v
- Comparator specification CH/CL +6v to –1v
- Parametric measurement unit per pin or system parametric measurement unit
- Power supply: 2 Hexvs (6 channels single quadrant) 5.5V/15A gangable to 90A and 1 HDVS (48 channels 2 quadrant) 7V/1A gang able to 4A

IV. Options available and installed

- MTO (Memory test Option): 16X-16Y – 32 DATA to 250 Mbit/S on 64 electronics pins
- DSCC (Digital Signal Source Capture) Max data rate: 800 Mbit/S on 256 pins
- Enhanced Timing Accuracy option: improve timing accuracy of HSDM pins (+/- 150 ps EPA).